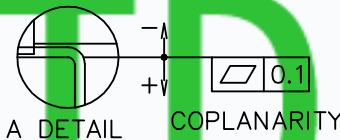
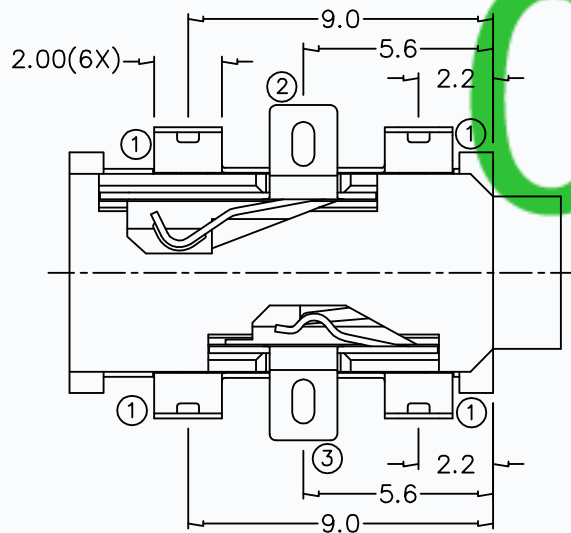
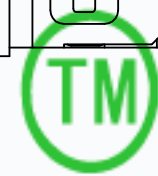
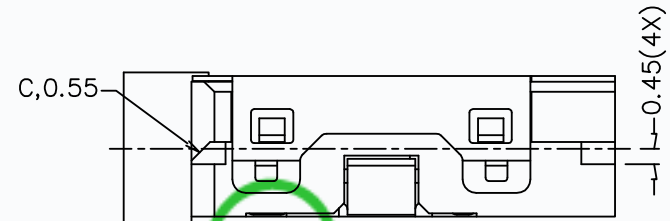
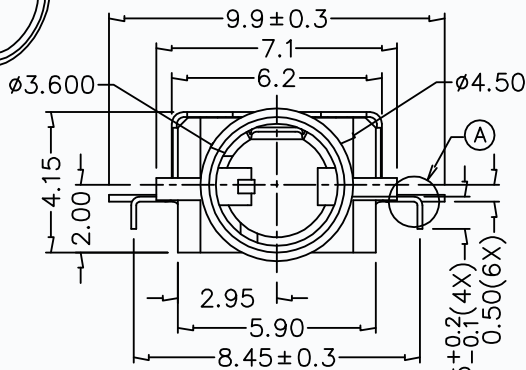
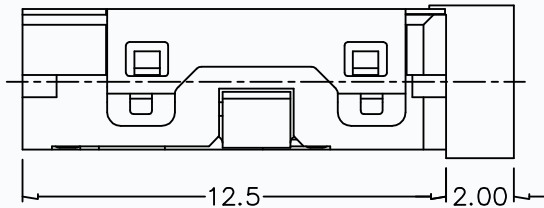
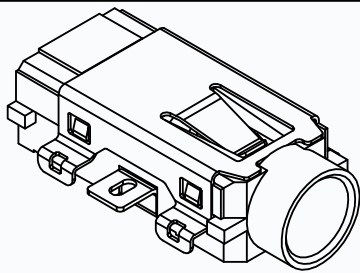


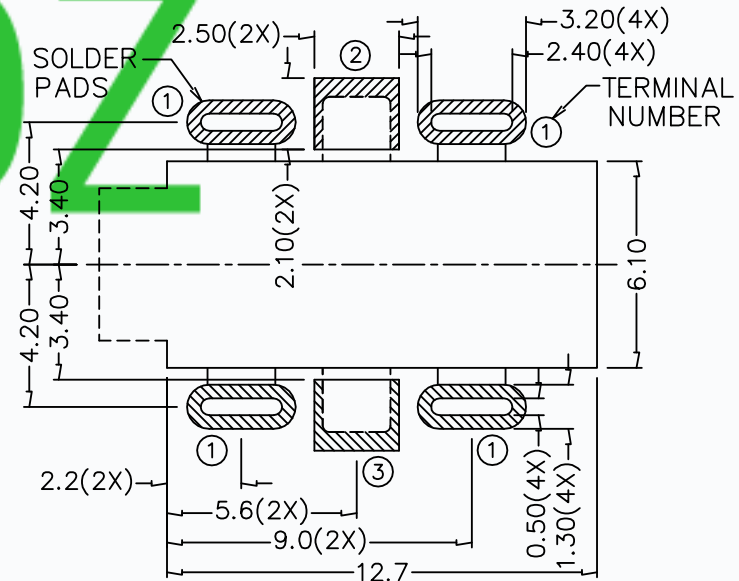
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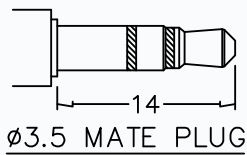
* MATERIAL

- TERMINAL 1 : STAINLESS STEEL
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- HOUSING : PA6T

MODEL NO.	T13-35033D
SCHMATIC	



RECOMMENDED SOLDER PAD LAYOUT



TOLERANCE
UNLESS SPECIFIED
WITHIN 1.5mm : ±0.1mm
OVER 1.5mm : ±0.2mm

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TITLE : 3.5mm SMD PHONE JACK

UNIT : mm

DRWG NO.: CMTDDZ-T13-3503D-00

MODEL: T13-3503D

SCALE: 3:1

DWN.	ERIC	2013-6-17
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CMTDDZ 东莞市田都电子有限公司
DONGGUAN TIANDU ELECTRONICS CO.,LTD.

CHK'D	MAIKO	2013-6-17
APPD.	Coco	2013-6-17

APPD.	DESCRIPTIONS OF REVISION
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